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N/A

PMP15037 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB	1		PMP15037	Any	Printed Circuit Board	
C1, C11	2	150uF	T495D157K010ATE100	Kemet	CAP, TA, 150 µF, 10 V, +/- 10%, 0.1 ohm, SMD	7343-31
C2, C12	2	10uF	GRM188R60J106ME47D	MuRata	CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0603	0603
C3, C6, C13	3	1uF	GRM188R71E105KA12D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0603	0603
C4, C5, C14, C15	4	22uF	GRM21BR61A226ME44L	MuRata	CAP, CERM, 22 µF, 10 V, +/- 20%, X5R, 0805	0805
C7, C17	2	10pF	GRM1885C2A100JA01D	MuRata	CAP, CERM, 10 pF, 100 V, +/- 5%, C0G/NP0, 0603	0603
C9, C19	2	1000pF	C0603C102K5RACTU	Kemet	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0603	0603
J1, J2, J5, J11, J12, J15	6		TSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	3x1 Header
J3, J4, J6, J13, J14, J16	6		TSW-102-07-G-S	Samtec	Header, 100mil, 2x1, Gold, TH	2x1 Header
L1, L11	2	470nH	XFL4015-471MEC	Coilcraft	Inductor, Shielded, Composite, 470 nH, 3.5 A, 0.0076 ohm, SMD	SMD, 4x4x1.5mm
Q11	1	25V	CSD16301Q2	Texas Instruments	MOSFET, N-CH, 25 V, 5 A, DQK0006C (WSON-6)	DQK0006C
R1	1	665k	RT0603DRE07665KL	Yageo America	RES, 665 k, 0.5%, 0.1 W, 0603	0603
R2	1	200k	RT0603BRD07200KL	Yageo America	RES, 200 k, 0.1%, 0.1 W, 0603	0603
R3	1	2.00Meg	CRCW06032M00FKEA	Vishay-Dale	RES, 2.00 M, 1%, 0.1 W, 0603	0603
R4, R12, R14	3	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
R5, R15	2	24.9k	CRCW060324K9FKEA	Vishay-Dale	RES, 24.9 k, 1%, 0.1 W, 0603	0603
R11	1	523k	CRCW0603523KFKEA	Vishay-Dale	RES, 523 k, 1%, 0.1 W, 0603	0603
Rs1, Rs11	2	0.3	CSRN2512FKR300	Stackpole Electronics Inc	RES, 0.3, 1%, 2 W, 2512	2512
TP1, TP2	2	Orange	5003	Keystone	Test Point, Miniature, Orange, TH	Orange Miniature Testpoint
U1, U11	2		TPS61021ADSGR	Texas Instruments	3-A BOOST CONVERTER WITH 0.5V ULTRA-LOW INPUT VOLTAGE, DSG0008A	DSG0008A

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